

We claim:

1. A device for climate control of a vehicle interior, comprising:
 - a coolant circuit in which coolant flows therethrough;
 - a compressor positioned in the coolant circuit;
 - a condenser positioned in the coolant circuit;
 - an evaporator positioned in the coolant circuit;
 - a heat transfer medium circuit in which a heat transfer medium flows therethrough;
 - a heat source positioned in the heat transfer medium circuit;
 - a heat exchanger positioned in the heat transfer medium circuit;
 - a heat/cold reservoir in which the evaporator and the heat exchanger are located; and
 - a heating/cooling surface for at least one of a driver's bed and vehicle interior wall, said heating/cooling surface being integrated into the heat transfer medium circuit such that at least one of a heat transfer medium flowing through the heat exchanger can flow selectively through the heating/cooling surface and a heat transfer medium being conveyed by the heat source can flow through the heating/cooling surface.
2. The device of claim 1, wherein the heating/cooling surface is arranged in a parallel connection to the heat exchanger in the heat transfer medium circuit.
3. The device of claim 1, further including a valve positioned to permit remote control of the flow of the heat transfer medium through the heating/cooling surface.
4. The device of claim 1, further including a second heating/cooling surface for at least one of a second driver's bed and a second vehicle interior wall, said second heating/cooling surface being located in a parallel connection to the first heating/cooling surface.
5. The device of claim 4, further including a first valve positioned to permit remote control of said first heating/cooling surface and a second valve positioned to permit remote control of said second heating/cooling surface.

6. The device of claim 4, further including a common valve is positioned to permit remote control of the flow of heat transfer medium to the parallel connection and thus to the first and second heating/cooling surfaces.

7. The device of claim 4, further including a second heat exchanger integrated into the heat transfer medium circuit and through which air flows.

8. The device of claim 7, wherein at least one of the first and second heating/cooling surfaces is series connected to the second heat exchanger, further including a bypass line positioned to bypass flow around said first and second heating/cooling surfaces and formed with an adjustable flow cross section.

9. The device of claim 7, wherein at least one of the first and the second heating/cooling surfaces is located in a parallel connection to the second heat exchanger.

10. The device of claim 1, further including a circulation pump integrated into the heat transfer medium circuit to convey the heat transfer medium through the heat exchanger and the heating/cooling surface.

11. The device of claim 10, further including a second heat exchanger integrated into the heat transfer medium circuit, wherein the circulation pump conveys the heat transfer medium through the second heat exchanger.

12. The device of claims 1, further including a second evaporator integrated into the coolant circuit and through which air flows.